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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Guoqiang Xing, et al.

Docket No: TI-31729

Serial No: 09/901,416

Conf. No: 7384

Examiner: Thanh T. Nguyen

Art Unit: 2813

Filed: 07/09/2001

For: DUAL HARDMASK PROCESS FOR THE FORMATION OF COPPER/LOW-K
INTERCONNECTS

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AMENDMENT UNDER 37 C.F.R. § 1.111

Assistant Commissioner For Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231 on 12-10-02.

Ann Trent
Ann Trent

Dear Sir:

Responsive to the Office Action mailed September 10, 2002, in connection with the above identified application, Applicants respectfully submit the following amendments and remarks.